Title (en)

Method for forming thick film layer of micro injecting device

Title (de)

Verfahren zum Bilden einer Dickfilmschicht für Mikrospritzvorrichtung

Title (fr)

Procédé de formation d'une couche à film épais pour micro-dispositif d'injection

Publication

EP 0999057 A3 20001129 (EN)

Application

EP 99308721 A 19991103

Priority

RU 98119888 A 19981103

Abstract (en)

[origin: EP0999057A2] A method for forming at thick film layer (30) of micro injecting device is disclosed in which a thin film layer (31') is formed on a substrate (1), a thick film layer (32') is formed on the thin film layer (31') without performing additional heat-treatment, and the thin film layer (31') and thick film layer (32') formed sequentially on the substrate are simultaneously heat-treated, to thereby complete a single thick film layer (30). The single thick film layer (30) is formed by a sequential coating process without being interfered by heat-treatment, thereby eliminating an isolating line. As a result, an overall durability of thick film layer (30) can be significantly enhanced. <IMAGE>

IPC 1-7

B41J 2/16

IPC 8 full level

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CPC (source: EP KR)

B41J 2/04 (2013.01 - KR); **B41J 2/14032** (2013.01 - EP); **B41J 2/1603** (2013.01 - EP); **B41J 2/1626** (2013.01 - EP); **B41J 2/1645** (2013.01 - EP)

Citation (search report)

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KR20170083504A

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

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EP 0999057 A2 20000510; **EP 0999057 A3 20001129**; CN 1253042 A 20000517; JP 2000141670 A 20000523; KR 20000034821 A 20000626; RU 2144472 C1 20000120

DOCDB simple family (application)

EP 99308721 A 19991103; CN 99126009 A 19991103; JP 31441099 A 19991104; KR 19990007326 A 19990305; RU 98119888 A 19981103